

Absolute Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V _{CBO}	-12	V
Collector-Emitter Voltage	V _{CEO}	-12	V
Emitter-Base Voltage	V _{EBO}	-7	V
Base Current	I _B	-500	mA
Continuous Collector Current	I _C	-3	A
Peak Pulse Collector Current	I _{CM}	-10	A

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

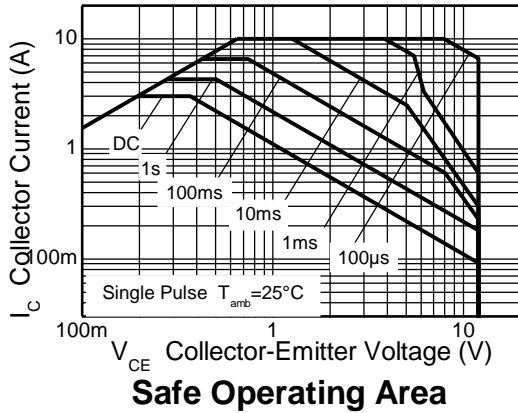
Characteristic	Symbol	Value	Unit
Power Dissipation Linear Derating Factor	P _D	1.1	W
		8.8	
Thermal Resistance, Junction to Ambient	R _{θJA}	1.7	mW/°C
		13.6	
Thermal Resistance, Junction to Ambient	R _{θJA}	113	°C/W
		73	
Thermal Resistance, Junction to Leads	R _{θJL}	30.0	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C

ESD Ratings (Note 8)

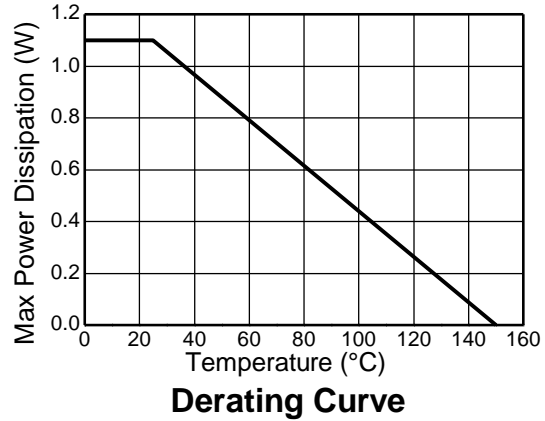
Characteristic	Symbol	Value	Unit	JEDEC Class
Electrostatic Discharge - Human Body Model	ESD HBM	4,000	V	3A
Electrostatic Discharge - Machine Model	ESD MM	400	V	C

- Notes:
- For a device mounted with collector leads on 25mm x 25mm 1oz copper that is on a single-sided 1.6mm FR4 PCB; device is measured under still air conditions whilst operating in a steady-state.
 - Same as Note 5, except the device is measured at t ≤ 5 seconds.
 - Thermal resistance from junction to solder-point (at the end of the collector leads).
 - Refer to JEDEC specification JESD22-A114 and JESD22-A115.

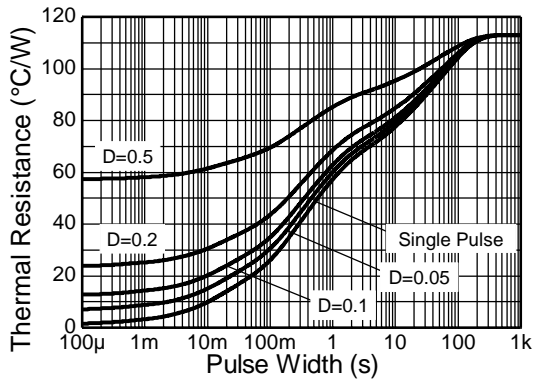
Thermal Characteristics and Derating Information



Safe Operating Area



Derating Curve



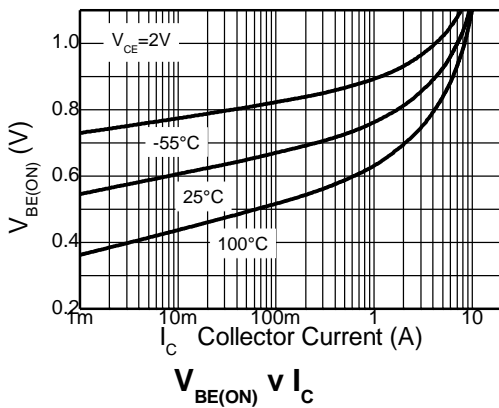
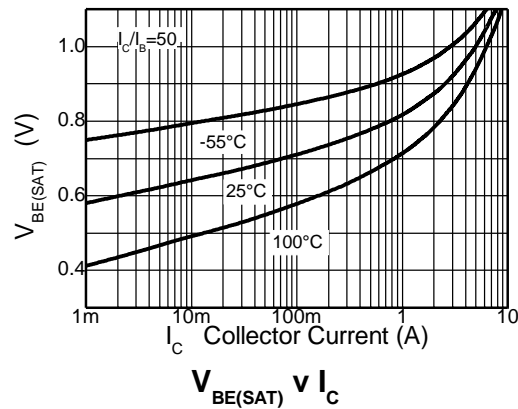
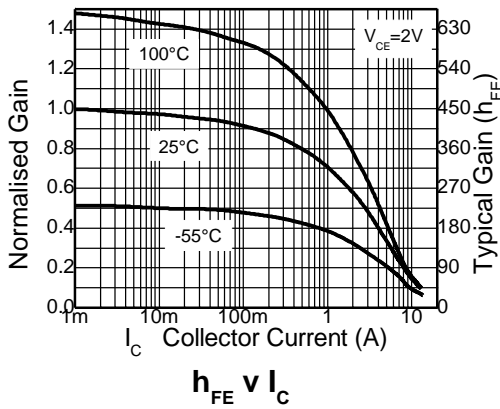
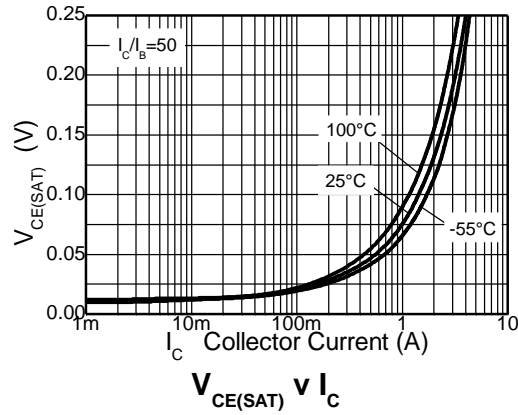
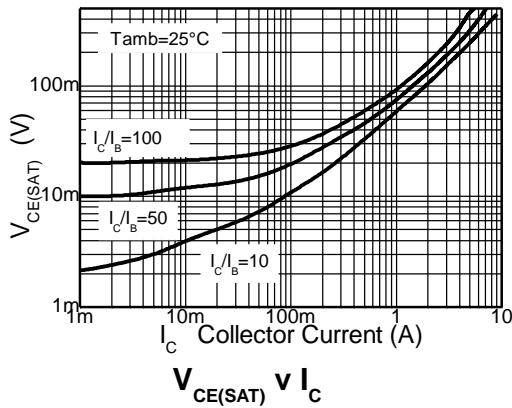
Transient Thermal Impedance

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS						
Collector-Base Breakdown Voltage	BV _{CBO}	-12	-35	—	V	I _C = -100μA
Collector-Emitter Breakdown Voltage (Note 9)	BV _{CEO}	-12	-25	—	V	I _C = -10mA
Emitter-Base Breakdown Voltage	BV _{EBO}	-7	-8.5	—	V	I _E = -100μA
Collector-Base Cutoff Current	I _{CBO}	—	<1	-100	nA	V _{CB} = -10V
Emitter Cutoff Current	I _{EBO}	—	<1	-100	nA	V _{EB} = -4V
Collector-Emitter Cutoff Current	I _{CES}	—	<1	-100	nA	V _{CES} = -10V
ON CHARACTERISTICS (Note 9)						
DC Current Gain (Note 9)	h _{FE}	300	475	—	—	I _C = -10mA, V _{CE} = -2V
		300	450	—	—	I _C = -0.1A, V _{CE} = -2V
		180	275	—	—	I _C = -2.5A, V _{CE} = -2V
		60	100	—	—	I _C = -8.0A, V _{CE} = -2V
		45	70	—	—	I _C = -10A, V _{CE} = -2V
Collector-Emitter Saturation Voltage (Note 9)	V _{CE(sat)}	—	-10	-17	mV	I _C = -0.1A, I _B = -10mA
		—	-100	-140		I _C = -1.0A, I _B = -10mA
		—	-100	-150		I _C = -1.5A, I _B = -50mA
		—	-195	-300		I _C = -3.0A, I _B = -50mA
Base-Emitter Saturation Voltage (Note 9)	V _{BE(sat)}	—	-0.90	-0.95	V	I _C = -3.0A, I _B = -50mA
Base-Emitter Turn-On Voltage (Note 9)	V _{BE(on)}	—	-0.85	-0.90	V	I _C = -3.0A, V _{CE} = -2V
SMALL SIGNAL CHARACTERISTICS						
Current Gain-Bandwidth Product	f _T	80	110	—	MHz	V _{CE} = -10V, I _C = -50mA, f = 100MHz
Output Capacitance	C _{obo}	—	21	30	pF	V _{CB} = -10V, f = 1MHz
Turn-On Time	t _(on)	—	70	—	ns	V _{CC} = -6V, I _C = -2A
Turn-Off Time	t _(off)	—	130	—	ns	I _{B1} = -I _{B2} = -50mA

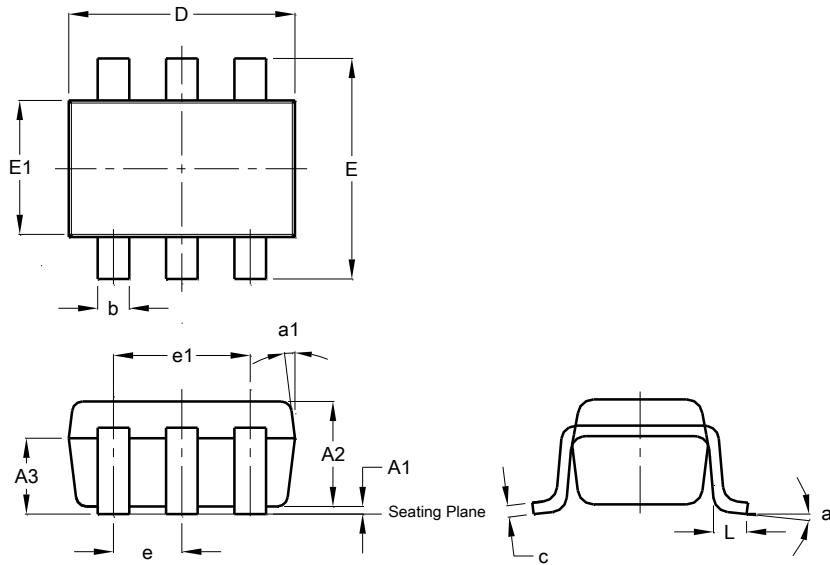
Note: 9. Measured under pulsed conditions. Pulse width ≤ 300μs. Duty cycle ≤ 2%.

Typical Electrical Characteristics (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)



Package Outline Dimensions

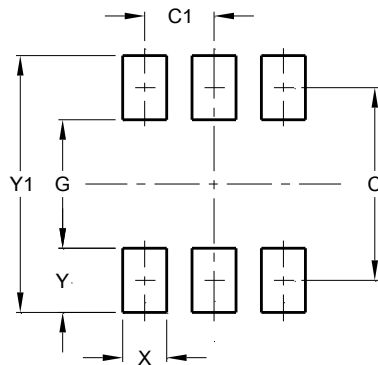
Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for the latest version.



SOT26			
Dim	Min	Max	Typ
A1	0.013	0.10	0.05
A2	1.00	1.30	1.10
A3	0.70	0.80	0.75
b	0.35	0.50	0.38
c	0.10	0.20	0.15
D	2.90	3.10	3.00
e	-	-	0.95
e1	-	-	1.90
E	2.70	3.00	2.80
E1	1.50	1.70	1.60
L	0.35	0.55	0.40
a	-	-	8°
a1	-	-	7°
All Dimensions in mm			

Suggested Pad Layout

Please see AP02001 at <http://www.diodes.com/datasheets/ap02001.pdf> for the latest version.



Dimensions	Value (in mm)
C	2.40
C1	0.95
G	1.60
X	0.55
Y	0.80
Y1	3.20

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